

**In the Drawings**

Please amend Fig. 5 as shown in red on the enclosed photoprint of the drawing page that includes FIG. 5, and as depicted on the enclosed "clean" copy of the drawing page that includes FIG. 5.

**In the Specification**

Please amend page 2, lines 8-16 of the specification as follows:

A1  
Fig. 6A is a plan view showing a conventional backing plate 104. Fig. 6B is a cross sectional view taken along the cross section line S5-S5 in Fig. 6A. The backing plate 104 is made of a metal such as copper or the like which is easily obtained and processed. Further, the backing plate 104 is formed so as to be mounted on the sputtering apparatus not shown in figure. The backing plate 104 provides the target 103 with a negative potential and also provided with a cooling means to prevent temperature increase.

Please also amend page 19, lines 9-12 of the specification as follows:

A2  
Figs. 7A and 7B are views showing another conventional backing plate: Fig. 7A is a plan view and Fig. 7B is a cross sectional view taken along a cross sectional line S6-S6 in Fig. 7A;

Please also amend page 22, lines 4-6 of the specification as follows:

A3 Then, particles scattered from the surface of the target 10 is adhered and deposited on the surface of the substrate 42 opposed to the target 10, thereby a thin film is formed.

Please also amend page 24, lines 13-19 of the specification as follows:

A4 The backing plate 1 is usually made of a material having good thermal conductivity, such as copper or aluminum alloy. In order to match a coefficient of thermal expansion of the target 10 with that of the backing plate, and in order to withstand a fluid pressure and an atmospheric pressure at the circulation of the cooling medium, materials, shape, and strength are determined in accordance with each case.